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U.S. UTILITY Patent Application

PATENT	NUMBER &	and
ISS	UE DATE	

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1	APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER		
H	10083440	02/26/2002	438	14	2812	Q. HOANG		
}	**APPLICANT	S: Ushiki T	akeo; Yaı	mada Keizo; I	lagaki Y	ohsuke; Tsujide Tohru;		
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		PPLICATIONS VEI	RIFIED:					
	JAPAN 2001-58	3075 03/02/2001						
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	Foreign priority clain	ned	. □ yes t			ATTORNEY DOCKET NO		
	35 USC 119 condition Verified and Acknow	ons met /ledged Examiners's int	□ yes (ials	⊒ no		NEKW 19.480		
	TITLE: Surface contamination analyzer for semiconductor wafers, method used therein and process							
	ioi labilicating se	miconductor device	9 		× ;	U.S.DEPT. OF COMM./PAT.8 TM-PTO-436L(Rev. 12-94)		
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NOTICE OF ALL	OWANCE MAILED		CLAIMS ALLOWED					
		Assistant Examiner	Total Claims		Print Claim for O.G			
ISSUE FEE			DRAWING					
Amount Due	Date Paid		Sheets Drwg.	Figs.Drwg.	Print Fig.			
		Primary Examiner						
TEF	RMINAL	PREPARED FOR ISSUE	Application Examiner					
	DISCLAMER	WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35.						